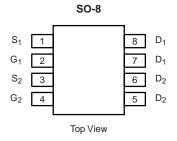


CEM8311-VB Datasheet Dual P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^{d, e}	Q _g (Typ.)			
- 30	0.021 at V _{GS} = - 10 V	- 8.0	15 nC			
- 30	0.028 at V _{GS} = - 4.5 V	- 7.0	15110			



FEATURES

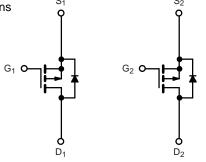
- · Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

Pb-free

RoHS

APPLICATIONS

- · Load Switches
 - Notebook PCs
 - Desktop PCs
 - Game Stations



P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$_{A}$ = 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	V
	T _C = 25 °C		- 9.5 ^e	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 8.0 ^e	
Continuous Diain Current (1) = 130 C)	T _A = 25 °C	l _D	- 8.3 ^{a, b}	
	T _A = 70 °C		- 7.9 ^{a, b}	
Pulsed Drain Current	I _{DM}	- 32 ^e		
0 1 0 0 0 1	T _C = 25 °C	I-	- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls –	- 2.0 ^{a, b}	
Avalanche Current	L = 0.1 mH	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mn	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Maximum Dawar Dissination	T _C = 70 °C	P _D	3.2	w
Maximum Power Dissipation	T _A = 25 °C		2.5 ^{a, b}	VV
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	-C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.
- e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 31		\//90
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ι _D = - 250 μΑ		4.5		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current	I	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	-1		- 1	,
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5 µA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α
D : 0	В	V _{GS} = - 10 V, I _D = - 7.3 A		0.021		0
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 6.2 A		0.028		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 9.1 A		23		S
Dynamic ^b						
Input Capacitance	C _{iss}			1350		pF
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		215		
Reverse Transfer Capacitance	C _{rss}			185		
Total Gate Charge		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -9.1 \text{ A}$		32	50	nC
	Q _g			15	25	
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -9.1 \text{ A}$		4		
Gate-Drain Charge	Q_{gd}			7.5		
Gate Resistance	R_{g}	f = 1 MHz		5.8		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		8	15	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		45	70	
Fall Time	t _f	_		12	25	
Turn-On Delay Time	t _{d(on)}			42	70	ns
Rise Time	ì,	V_{DD} = - 15 V, R_L = 15 Ω		35	60	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	70	
Fall Time	ì _f			16	30	
Drain-Source Body Diode Characterist	ics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	۸
Pulse Diode Forward Current	I _{SM}				- 32	Α
Body Diode Voltage	V _{SD}	I _S = -2 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			34	60	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1 2 A d1/d+ 400 A/: T 05 00		22	40	nC
Reverse Recovery Fall Time		t_a $t_{F} = -2 A$, $di/dt = 100 A/\mu s$, $t_{J} = 25 C$		11		ns
Reverse Recovery Rise Time	t _b			23		

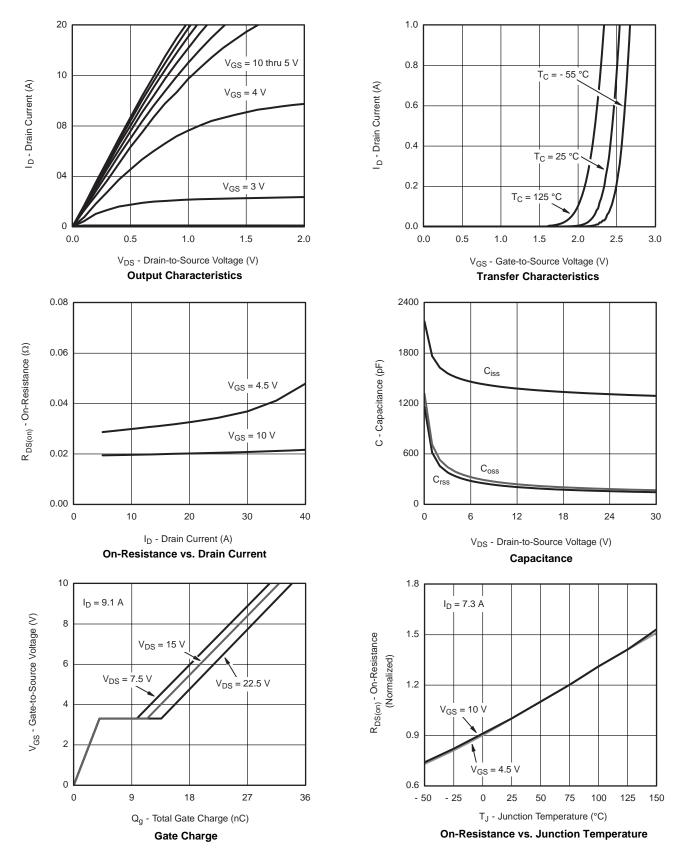
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

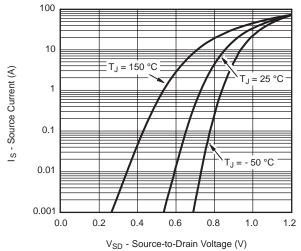
a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

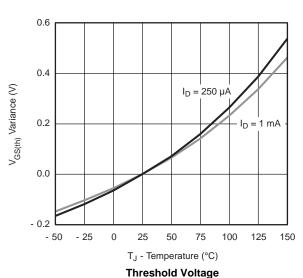








Source-Drain Diode Forward Voltage



0.10

O .08

O .08

O .004

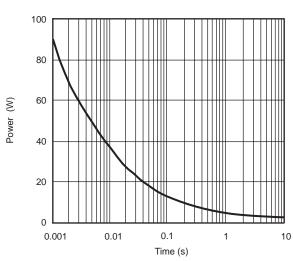
O .004

O .002

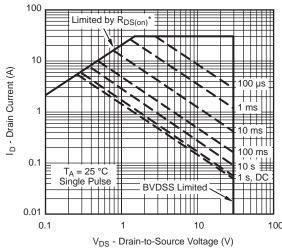
O .000

O

 $\label{eq:VGS} V_{GS} \mbox{ - Gate-to-Source Voltage (V)} \\$ On-Resistance vs. Gate-to-Source Voltage



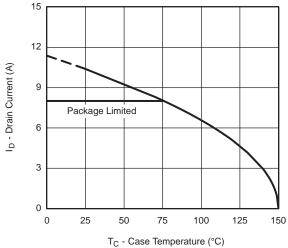
Single Pulse Power, Junction-to-Ambient



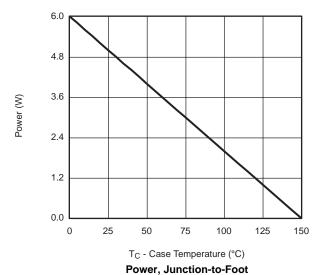
 v_{DS} - Drain-to-Source voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

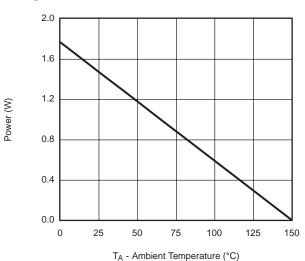
Safe Operating Area





Current Derating*

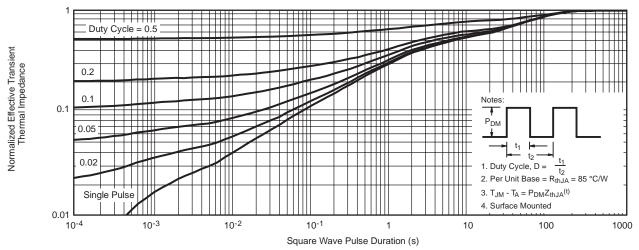




Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package





Normalized Thermal Transient Impedance, Junction-to-Ambient

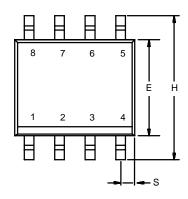


Normalized Thermal Transient Impedance, Junction-to-Foot



7

SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







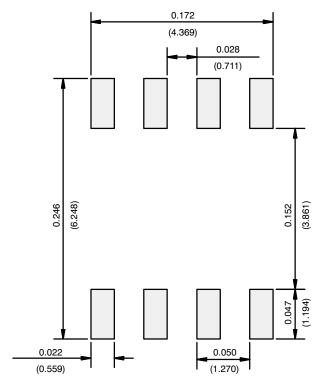
	MILLIMETERS		INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev I 11-Sen-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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